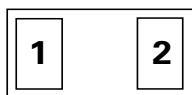


## SP1007 Series 3.5pF 8kV Bidirectional Discrete TVS

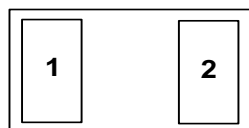


### Pinout

0201 Flipchip



SOD882



### Functional Block Diagram



### Additional Information



[Datasheet](#)



[Resources](#)



[Samples](#)

### Description

The SP1007 includes back-to-back Zener diodes fabricated in a proprietary silicon avalanche technology to provide protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at the maximum level specified in the IEC61000-4-2 international standard (Level 4,  $\pm 8\text{kV}$  contact discharge) without performance degradation. The back-to-back configuration provides symmetrical ESD protection for data lines when AC signals are present.

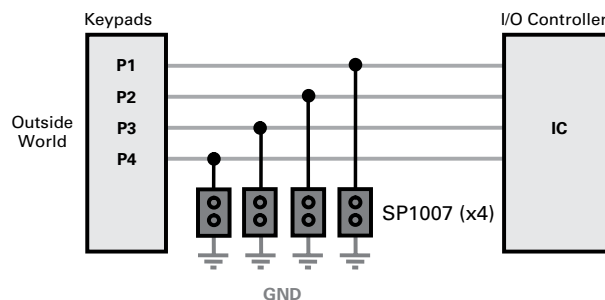
### Features

- ESD, IEC61000-4-2,  $\pm 8\text{kV}$  contact,  $\pm 15\text{kV}$  air
- EFT, IEC61000-4-4, 40A (5/50ns)
- Lightning, IEC61000-4-5, 2A ( $t_p=8/20\mu\text{s}$ )
- Low capacitance of 5pF (TYP @  $V_R=5\text{V}$ )
- Low leakage current of  $0.1\mu\text{A}$  at 5V
- Space efficient 0201 and 0402 footprint

### Applications

- Mobile Phones
- Smart Phones
- Camcorders
- Portable Medical
- Digital Cameras
- MP3/PMP
- Portable Navigation Devices
- Tablets
- Point of Sale Terminals

### Application Example



Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	2.0	A
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

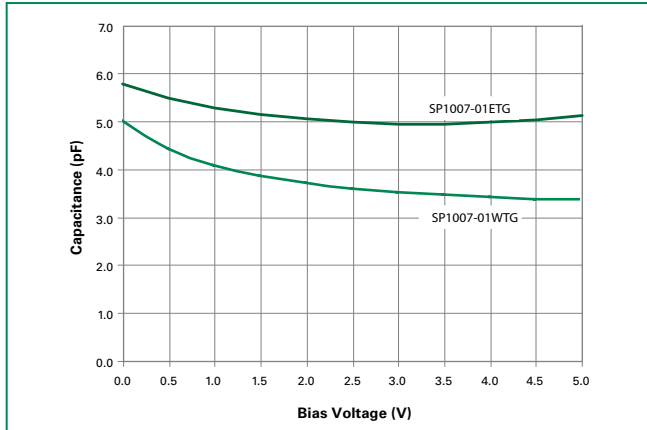
### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$				6.0	V
Breakdown Voltage	$V_{BR}$	$I_R=1mA$		8.5	9.5	V
Leakage Current	$I_{LEAK}$	$V_R=5V$ with 1 pin at GND		0.1	0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		11.2		V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		13.1		V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.9		$\Omega$
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC61000-4-2 (Contact Discharge)	$\pm 8$			kV
		IEC61000-4-2 (Air Discharge)	$\pm 15$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V		5	6	pF

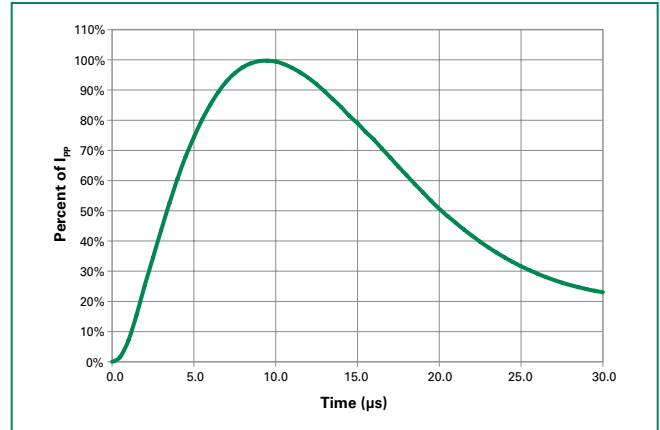
Note:

<sup>1</sup>Parameter is guaranteed by design and/or device characterization.

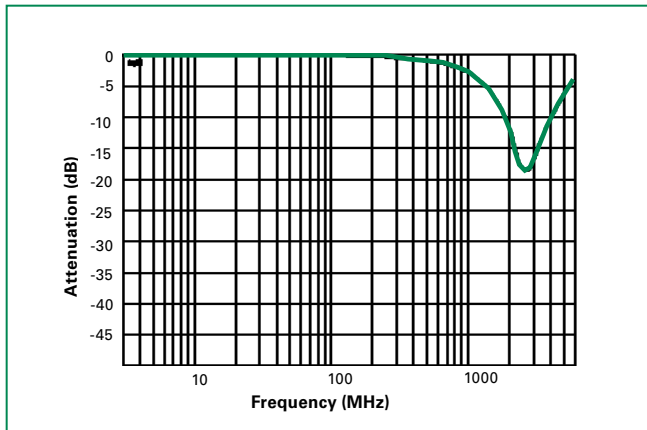
**Capacitance vs. Reverse Bias**



**Pulse Waveform**



**Insertion Loss (S21) I/O to GND**



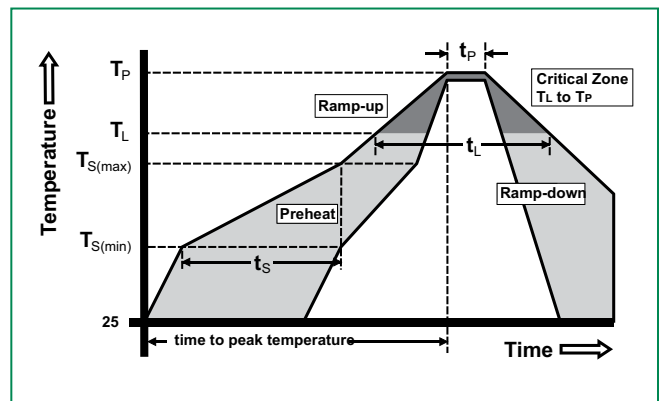
**Product Characteristics of SOD-882 Package**

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substitute Material</b>	Silicon
<b>Body Material</b>	Molded Epoxy
<b>Flammability</b>	UL 94 V-0

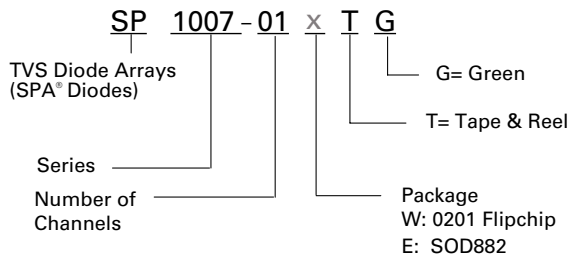
- Notes :
1. All dimensions are in millimeters
  2. Dimensions include solder plating.
  3. Dimensions are exclusive of mold flash & metal burr.
  4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
  5. Package surface matte finish VDI 11-13.

**Soldering Parameters**

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes Max.
<b>Do not exceed</b>		260°C



**Part Numbering System**



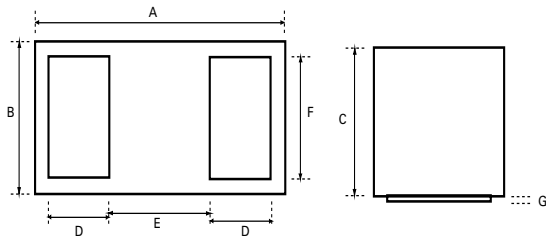
**Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP1007-01WTG	0201 Flipchip	••	10,000
SP1007-01ETG	SOD882	•b	10,000

**Part Marking System**

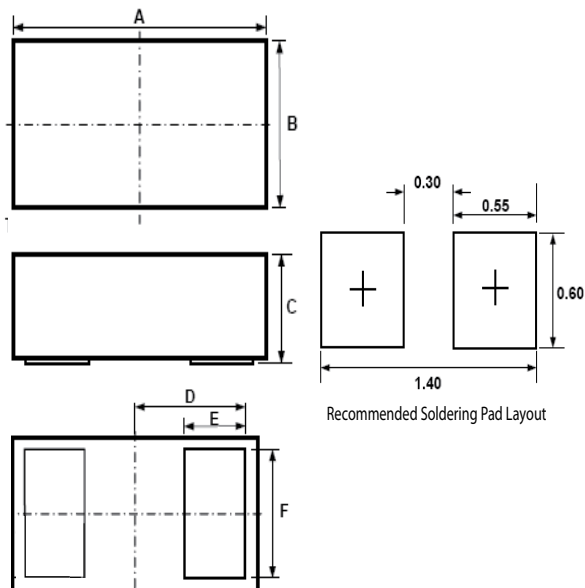


**Package Dimensions — 0201 Flip Chip**



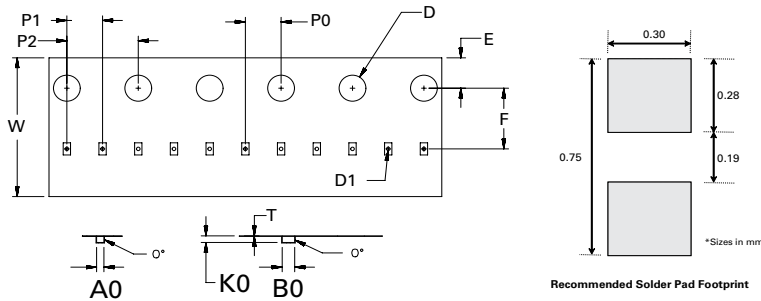
Symbol	0201 Flipchip					
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
<b>A</b>	0.595	0.620	0.645	0.0234	0.0244	0.0254
<b>B</b>	0.295	0.320	0.345	0.0116	0.0126	0.0136
<b>C</b>	0.245	0.275	0.305	0.0096	0.0108	0.0120
<b>D</b>	0.145	0.150	0.155	0.0057	0.0059	0.0061
<b>E</b>	0.245	0.250	0.255	0.0096	0.0098	0.0100
<b>F</b>	0.245	0.250	0.255	0.0096	0.0098	0.0100
<b>G</b>	0.005	0.010	0.015	0.0002	0.0004	0.0006

**Package Dimensions — SOD882**



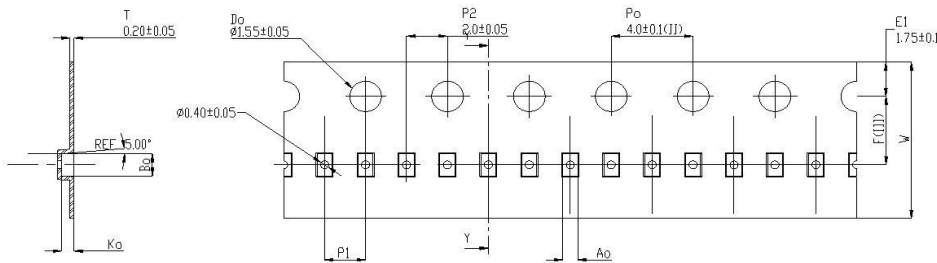
Symbol	Package	SOD882				
	JEDEC	MO-236				
	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
<b>A</b>	0.90	1.00	1.10	0.035	0.039	0.043
<b>B</b>	0.50	0.60	0.70	0.020	0.024	0.028
<b>C</b>	0.40	0.50	0.60	0.016	0.020	0.024
<b>D</b>		0.45		0.018		
<b>E</b>	0.20	0.25	0.35	0.008	0.010	0.012
<b>F</b>	0.45	0.50	0.55	0.018	0.020	0.022

**Embossed Carrier Tape & Reel Specification – 0201 Flipchip**



Symbol	Millimeters
<b>A0</b>	0.41±0.03
<b>B0</b>	0.70±0.03
<b>D</b>	∅ 1.50 + 0.10
<b>D1</b>	∅ 0.20 ± 0.05
<b>E</b>	1.75±0.10
<b>F</b>	3.50±0.05
<b>K0</b>	0.38±0.03
<b>P0</b>	2.00±0.05
<b>P1</b>	2.00±0.05
<b>P2</b>	4.00±0.10
<b>W</b>	8.00 + 0.30 -0.10
<b>T</b>	0.23±0.02

**Embossed Carrier Tape & Reel Specification – SOD882**



Symbol	Millimeters
<b>A0</b>	0.70±0.045
<b>B0</b>	1.10±0.045
<b>K0</b>	0.65±0.045
<b>F</b>	3.50±0.05
<b>P1</b>	2.00±0.10
<b>W</b>	8.00 + 0.30 -0.10

